

## **Preliminary Product Information Sheet**

### EPO-TEK® OG147-51 (formerly 90-76-2)

Note: These are typical properties to be used as a guide only, not a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results.

Date:	September 2017	Recommended Cure: 120°C / 1 Hour
Rev:	V	
No. of Components:	Single	Minimum Alternative Cure(s):
Mix Ratio by Weight:	N/A	May not achieve performance properties listed below
Specific Gravity:	1.30	150°C / 5 Minutes
Pot Life:	28 Days	125°C / 20 Minutes
Shelf Life- Bulk:	One year refrigerated	

#### NOTES:

• Container(s) should be kept closed when not in use.

• Filled systems should be stirred thoroughly before mixing and prior to use.

• Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

**Product Description:** A single component, semi-flexible epoxy adhesive designed for low stress bonding of fiber optic component applications. It is a thixotropic adhesive which can be applied by dispensing or screen printing techniques. It has a very long pot-life, capable of fast curing techniques.

## MATERIAL CHARACTERISTICS\*:

PHYSICAL PROPERTIES:		Cure condition	: 120°C / 1 Hour	
Color (before cure):		Black		
Consistency:		Smooth paste		
Viscosity (23°C) @ 100 rpm:		1,864	cPs	
Thixotropic Index:		2.7		
Glass Transition Temp:		33	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)	
Coefficient of Thermal Expans	ion (CTE):			
	Below Tg:	57	x 10 <sup>-6</sup> in/in°C	
	Above Tg:	178	x 10 <sup>-6</sup> in/in°C	
Shore D Hardness:	C C	84		
Lap Shear @ 23°C:			psi	
Die Shear @ 23°C:		17	Kg	
Degradation Temp:		376	°Č	
Weight Loss:				
	@ 200°C:	< 0.05	%	
	@ 250°C:	0.15	%	
	@ 300°C:	0.75	%	
Suggested Operating Temperature:		< 300	°C (Intermittent)	
Storage Modulus:		142,857	psi	
Particle Size:		≤ 20	microns	
OPTICAL PROPERTIES @ 23°C:				
Spectral Transmission:	< 20% @ 300-1600		nm	
Refractive Index:		N/A		

# The data above is INITIAL only - it may be changed at any time, for any reason without notice to anyone. It is provided only as a guide for evaluation/consideration.

\* These material characteristics are typical properties that are based on a limited number of samples/batches. All properties are based on the cure indicated above. Some properties may vary as manufactured quantities are scaled up to commercialized production levels.

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